

ABSTRACT OF THE DISCLOSURE

An apparatus and method determine a size of a bonding film for bonding a bonding target having a size which varies due to temperature variation, at an environmental temperature which is different from a temperature during use. The method includes measuring an actual size of the bonding portion of the circuit electrode at the first temperature, comparing the actual size of the bonding portion with a designed size of the bonding portion at the first temperature, and determining a cutting size of the bonding material based on a comparison result and mounting the bonding material over the bonding portion.